BT131-600

4Q Triac

6 May 2015 **Product data sheet**

1. General description

Planar passivated very sensitive gate four quadrant triac in a SOT54 plastic package intended for interfacing with low power drivers including microcontrollers.

2. Features and benefits

- Direct interfacing to logic level ICs
- Direct interfacing to low power gate drive circuits and microcontrollers
- High blocking voltage capability
- Planar passivated for voltage ruggedness and reliability
- Triggering in all four quadrants
- Very sensitive gate

3. Applications

- Air conditioner indoor fan control
- General purpose motor control
- General purpose switching

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{DRM}	repetitive peak off-state voltage			-	-	600	V
I_{TSM}	non-repetitive peak on-state current	full sine wave; $T_{j(init)}$ = 25 °C; t_p = 20 ms; Fig. 4; Fig. 5		-	-	12.5	A
T_j	junction temperature			-	-	125	°C
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{lead} \leq$ 51.2 °C; Fig. 1; Fig. 2; Fig. 3		-	-	1	A
Static characteristics							
I_{GT}	gate trigger current	V_D = 12 V; I_T = 0.1 A; T2+ G+; T_j = 25 °C; Fig. 7		-	0.4	3	mA
		V_D = 12 V; I_T = 0.1 A; T2+ G-; T_j = 25 °C; Fig. 7		-	1.3	3	mA

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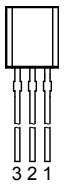
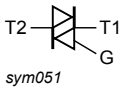
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
		V_D = 12 V; I_T = 0.1 A; T2- G-; T_j = 25 °C; Fig. 7		-	1.4	3	mA
		V_D = 12 V; I_T = 0.1 A; T2- G+; T_j = 25 °C; Fig. 7		-	3.8	7	mA
Dynamic characteristics							
dV_D/dt	rate of rise of off-state voltage	V_{DM} = 402 V; T_j = 125 °C; R_{GT1} = 1 kΩ; (V_{DM} = 67% of V_{DRM}); exponential waveform; Fig. 12		10	20	-	V/µs

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T2	main terminal 2	 **TO-92 (SOT54)**	 *sym051*
2	G	gate		
3	T1	main terminal 1		

6. Ordering information

Table 3. Ordering information

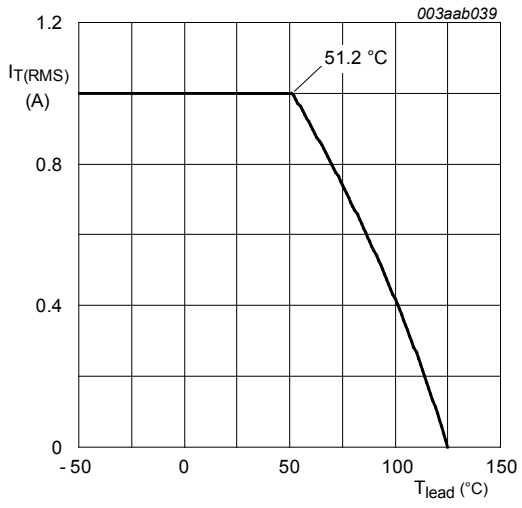
Type number	Package		
	Name	Description	Version
BT131-600	TO-92	plastic single-ended leaded (through hole) package; 3 leads	SOT54
BT131-600/DG	TO-92	plastic single-ended leaded (through hole) package; 3 leads	SOT54

7. Limiting values

Table 4. Limiting values

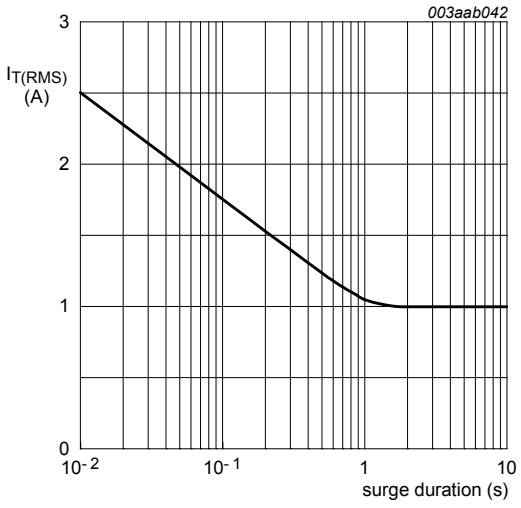
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{DRM}	repetitive peak off-state voltage			-	600	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{lead} \leq 51.2$ °C; Fig. 1; Fig. 2; Fig. 3		-	1	A
I_{TSM}	non-repetitive peak on-state current	full sine wave; $T_{j(init)} = 25$ °C; $t_p = 20$ ms; Fig. 4; Fig. 5		-	12.5	A
		full sine wave; $T_{j(init)} = 25$ °C; $t_p = 16.7$ ms		-	13.7	A
I^2t	I^2t for fusing	$t_p = 10$ ms; sine-wave pulse		-	0.78	A^2s
dI_T/dt	rate of rise of on-state current	$I_G = 6$ mA; T2+ G+		-	50	A/µs
		$I_G = 6$ mA; T2+ G-		-	50	A/µs
		$I_G = 14$ mA; T2- G+		-	10	A/µs
		$I_G = 6$ mA; T2- G-		-	50	A/µs
I_{GM}	peak gate current			-	2	A
P_{GM}	peak gate power			-	5	W
$P_{G(AV)}$	average gate power	over any 20 ms period		-	0.1	W
T_{stg}	storage temperature			-40	150	°C
T_j	junction temperature			-	125	°C



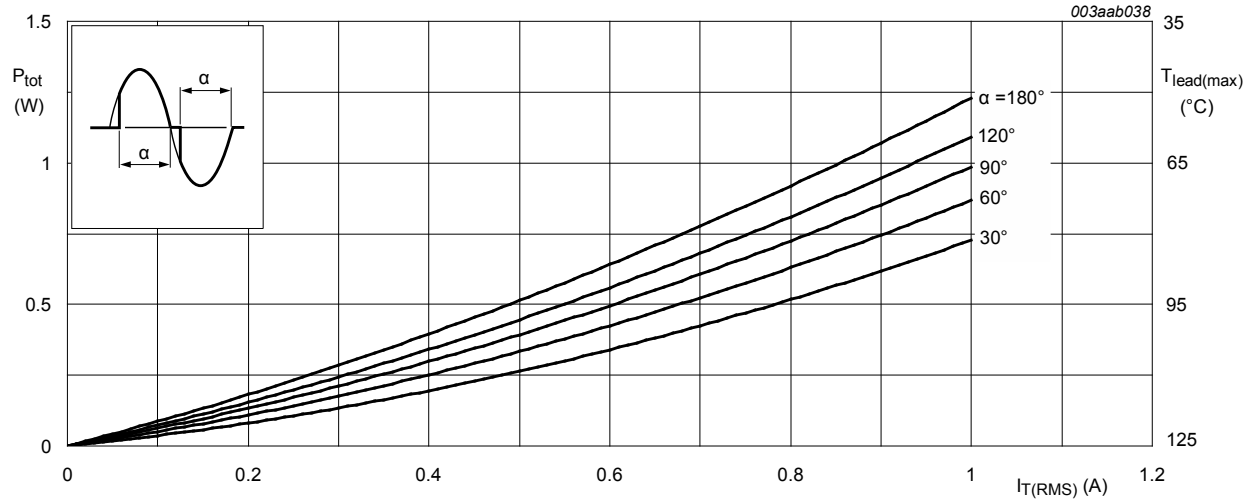
$T_{lead} = 51.2$ °C

Fig. 1. RMS on-state current as a function of lead temperature; maximum values



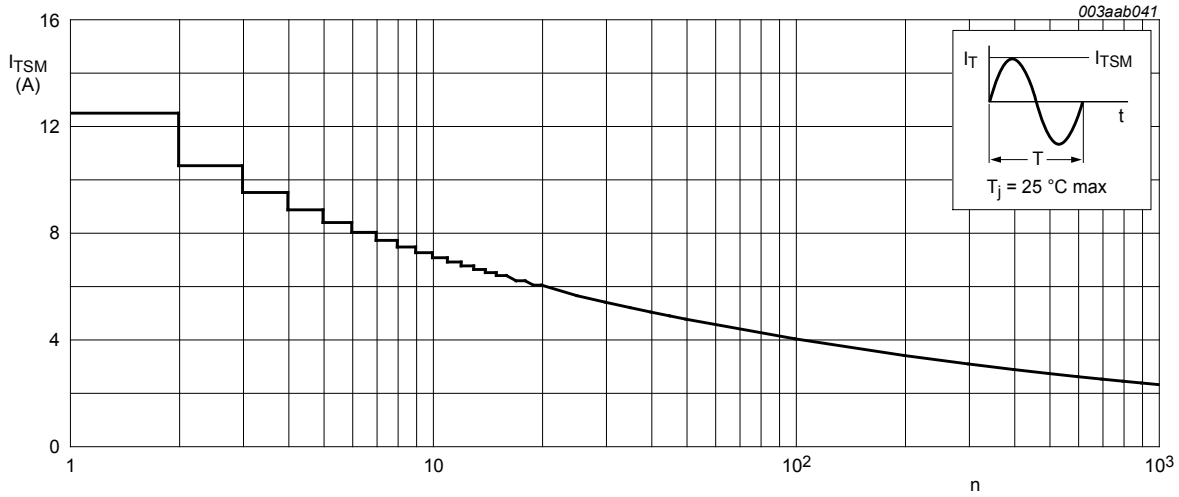
f = 50 Hz; $T_{lead} = 51.2$ °C

Fig. 2. RMS on-state current as a function of surge duration; maximum values



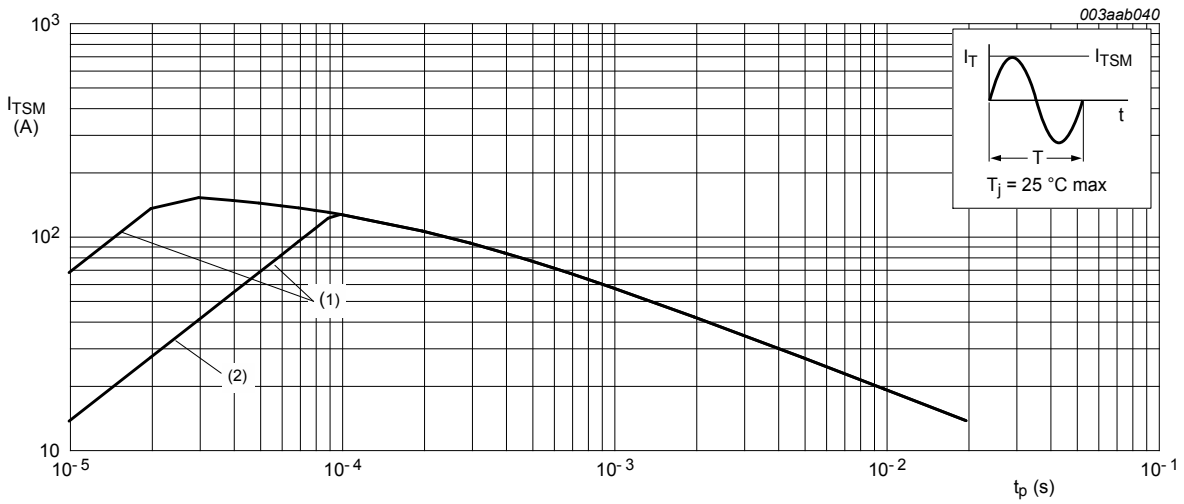
α = conduction angle

Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values



f = 50 Hz

Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



$t_p \leq 20$ ms

(1) dI_T/dt limit

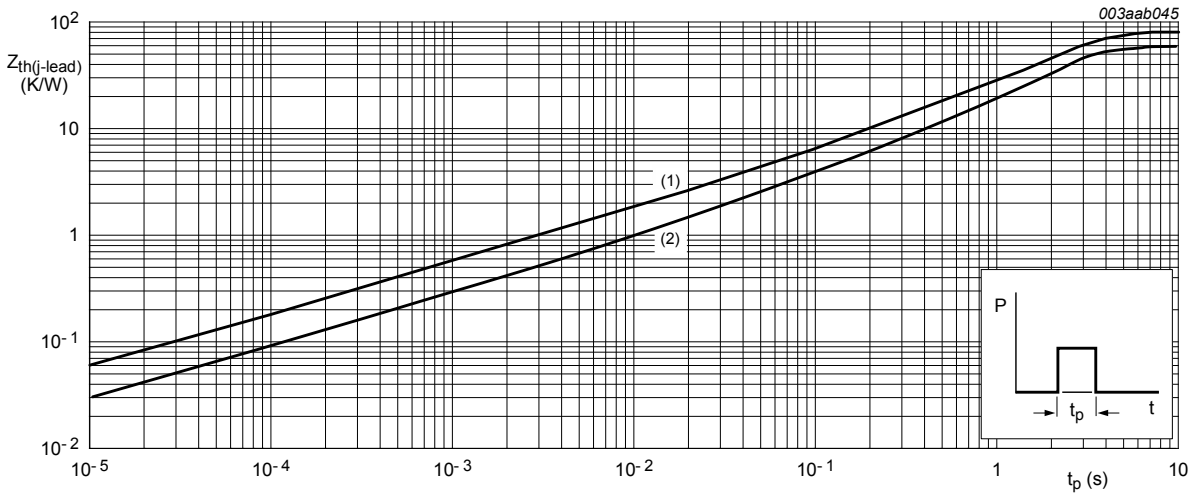
(2) T2- G+ quadrant

Fig. 5. Non-repetitive peak on-state current as a function of pulse width for sinusoidal currents; maximum values

8. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j\text{-}lead)}$	thermal resistance from junction to lead	full cycle; Fig. 6		-	-	60	K/W
		half cycle; Fig. 6		-	-	80	K/W
$R_{th(j\text{-}a)}$	thermal resistance from junction to ambient	printed circuit board mounted: lead length = 4 mm		-	150	-	K/W



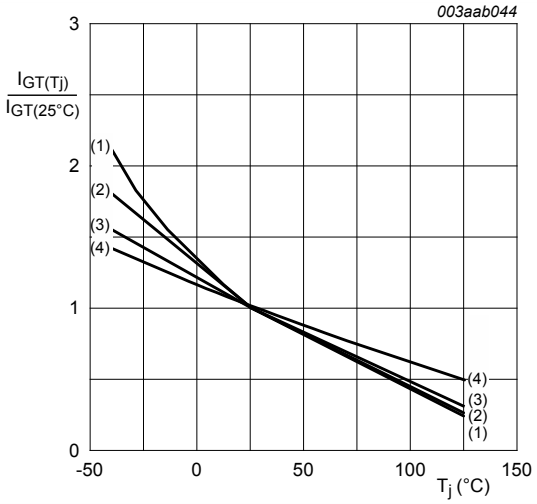
(1) Unidirectional (half cycle)
(2) Bidirectional (full cycle)

Fig. 6. Transient thermal impedance from junction to lead as a function of pulse width

9. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
I_{GT}	gate trigger current	V_D = 12 V; I_T = 0.1 A; T2+ G+; T_j = 25 °C; Fig. 7		-	0.4	3	mA
		V_D = 12 V; I_T = 0.1 A; T2+ G-; T_j = 25 °C; Fig. 7		-	1.3	3	mA
		V_D = 12 V; I_T = 0.1 A; T2- G-; T_j = 25 °C; Fig. 7		-	1.4	3	mA
		V_D = 12 V; I_T = 0.1 A; T2- G+; T_j = 25 °C; Fig. 7		-	3.8	7	mA
I_L	latching current	V_D = 12 V; I_G = 0.1 A; T2+ G+; T_j = 25 °C; Fig. 8		-	1.2	5	mA
		V_D = 12 V; I_G = 0.1 A; T2+ G-; T_j = 25 °C; Fig. 8		-	4	8	mA
		V_D = 12 V; I_G = 0.1 A; T2- G-; T_j = 25 °C; Fig. 8		-	1	5	mA
		V_D = 12 V; I_G = 0.1 A; T2- G+; T_j = 25 °C; Fig. 8		-	2.5	8	mA
I_H	holding current	V_D = 12 V; T_j = 25 °C; Fig. 9		-	1.3	5	mA
V_T	on-state voltage	I_T = 1.4 A; T_j = 25 °C; Fig. 10		-	1.2	1	V
V_{GT}	gate trigger voltage	V_D = 12 V; I_T = 0.1 A; T_j = 25 °C; Fig. 11		-	0.7	1	V
		V_D = 400 V; I_T = 0.1 A; T_j = 125 °C; Fig. 11		0.2	0.3	-	V
I_D	off-state current	V_D = 600 V; T_j = 125 °C		-	0.1	0.5	mA
Dynamic characteristics							
dV_D/dt	rate of rise of off-state voltage	V_{DM} = 402 V; T_j = 125 °C; R_{GT1} = 1 kΩ; (V_{DM} = 67% of V_{DRM}); exponential waveform; Fig. 12		10	20	-	V/µs
dV_{com}/dt	rate of change of commutating voltage	V_D = 400 V; T_j = 125 °C; dI_{com}/dt = 0.5 A/ms; I_T = 1 A; gate open circuit		2	-	-	V/µs
t_{gt}	gate-controlled turn-on time	I_{TM} = 1.5 A; V_D = 600 V; I_G = 0.1 A; dI_G/dt = 5 A/µs		-	2	-	µs



(1) T2- G+
(2) T2- G-
(3) T2+ G-
(4) T2+ G+

Fig. 7. Normalized gate trigger current as a function of junction temperature

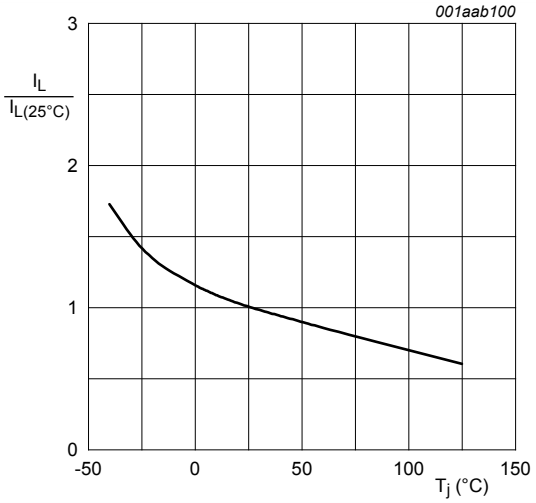


Fig. 8. Normalized latching current as a function of junction temperature

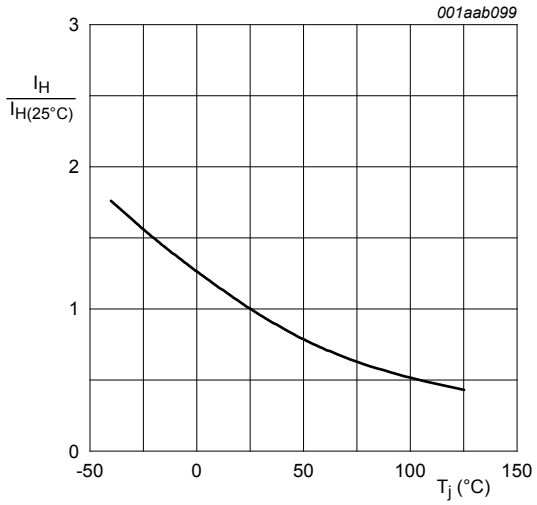
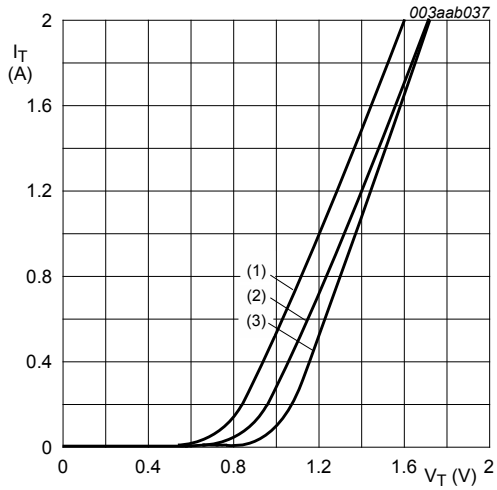


Fig. 9. Normalized holding current as a function of junction temperature



V_o = 0.92 V; R_s = 0.4 Ω
(1) T_j = 125 °C; typical values
(2) T_j = 125 °C; maximum values
(3) T_j = 25 °C; maximum values

Fig. 10. On-state current as a function of on-state voltage

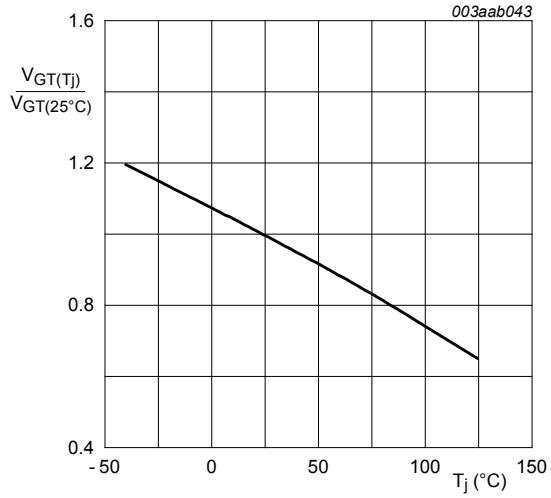


Fig. 11. Normalized gate trigger voltage as a function of junction temperature

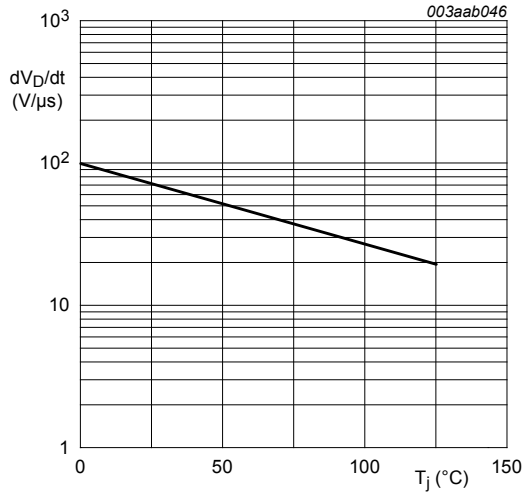
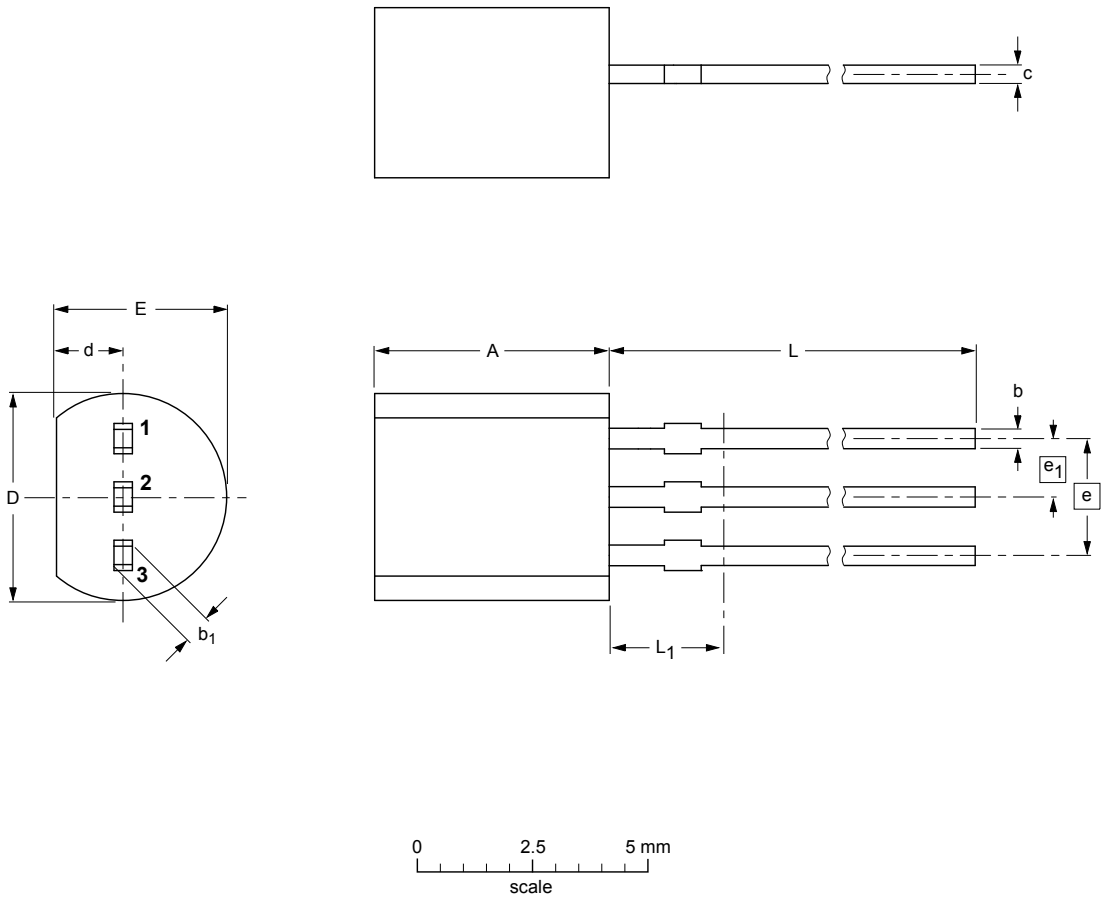


Fig. 12. Rate of rise of off-state voltage as a function of junction temperature; typical values

10. Package outline

Plastic single-ended leaded (through hole) package; 3 leads **SOT54**



DIMENSIONS (mm are the original dimensions)

UNIT	A	b	b_1	c	D	d	E	e	e_1	L	L_1 (1) max.
mm	5.2 5.0	0.48 0.40	0.66 0.55	0.45 0.38	4.8 4.4	1.7 1.4	4.2 3.6	2.54	1.27	14.5 12.7	2.5

Note

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT54		TO-92	SC-43A			~~04-06-28~~ 04-11-16

Fig. 13. Package outline TO-92 (SOT54)

11. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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12. Contents

1 General description 1
2 Features and benefits 1
3 Applications 1
4 Quick reference data 1
5 Pinning information 2
6 Ordering information 2
7 Limiting values 3
8 Thermal characteristics 6
9 Characteristics 7
10 Package outline 10
11 Legal information 11
11.1 Data sheet status 11
11.2 Definitions 11
11.3 Disclaimers 11
11.4 Trademarks 12

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